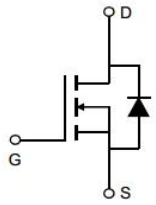
迈诺斯科技

MPG08N68

68V N-Channel Power MOSFET

DESCRIPTION

The MPG08N68 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.



Schematic diagram

TO-220

TO-263

KEY CHARACTERISTICS

① V_{DS} = 68V,I_D = 100A

② $R_{DS(ON)}$ < 7.5mΩ @ V_{GS}=10V

③ Special process technology for high ESD capability

④ High density cell design for ultra low R_{dson}

⑤ Fully characterized avalanche voltage and current

⑥ Good stability and uniformity with high EAS

⑦ Excellent package for good heat dissipation

Application

① Power switching application

② Hard switched and High frequency circuits

③ Uninterruptible power supply

Package Marking And Ordering Information

Device Marking	Ordering Codes	Package	Product Code	Packing
08N68	MPG08N68-S	TO-263	MPG08N68S	Reel
08N68	MPG08N68-P	TO-220	MPG08N68P	Tube

Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	68	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	100	A
Drain Current-Pulsed (Note 1)	I_{DM}	340	A
Maximum Power Dissipation(Tc=25℃)	P_D	125	W
Single pulse avalanche energy(Note 2)	E_{AS}	370	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 175	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case	$R_{\theta JC}$	1.2	℃/W

Electrical Characteristics (TA=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	68	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=68V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	2	3	4	V
Drain-Source On-State Resistance(Note 3)	$R_{DS(ON)}$	V_{GS}=10V, I_D=45A	-	6.5	7.5	mΩ
Forward Transconductance	G_{FS}	V_{DS}=10V,I_D=20A	-	20	-	S
Dynamic Characteristics						
Input Capacitance	C_{lss}	V_{DS}=30V,V_{GS}=0V, F=1.0MHz	-	3200	-	pF
Output Capacitance	C_{oss}		-	440	-	pF
Reverse Transfer Capacitance	C_{rss}		-	180	-	pF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=30V, ID=30A, V_{GS}=10V,R_{GEN}=6Ω	-	16	-	nS
Turn-on Rise Time	t_r		-	95	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	47	-	nS
Turn-Off Fall Time	t_f			31	-	nS
Total Gate Charge	Q_g	V_{DS}=30V,I_D=20A V_{GS}=10V	-	40	-	nC
Gate-Source Charge	Q_{gs}		-	11	-	nC
Gate-Drain Charge	Q_{gd}		-	15	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage(Note 3)	V_{SD}	V_{GS}=0V,I_S=90A	-	-	1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. E_{AS} condition :T_j=25℃,V_{DD}=30V,V_G=10V,L=0.5mH,Rg=25Ω
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production.

Characteristics Curves

Figure 1 Output Characteristics

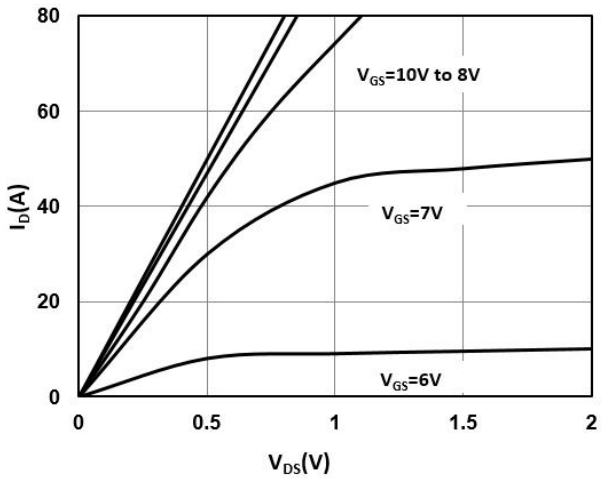


Figure 2 Transfer Characteristics

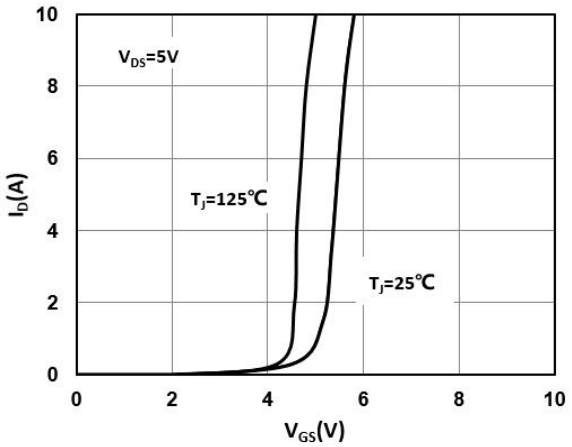


Figure 3 On-Resistance vs. I_D and V_{GS}

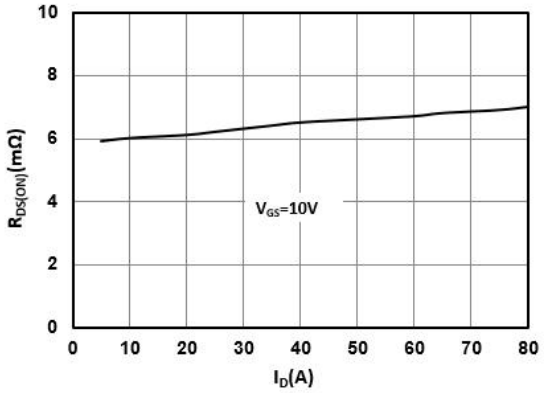


Figure 4 On-Resistance vs. Junction Temperature

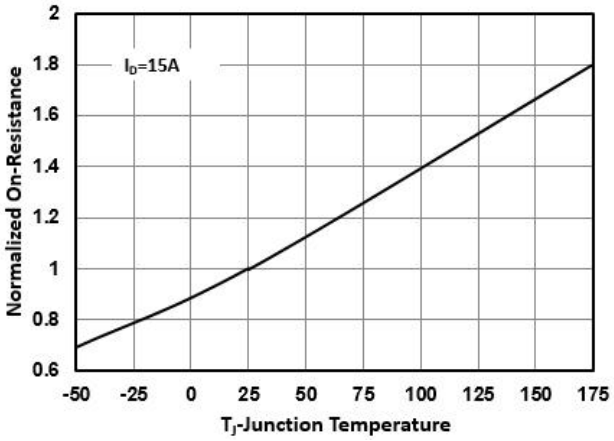


Figure 5 On-Resistance vs. V_{GS}

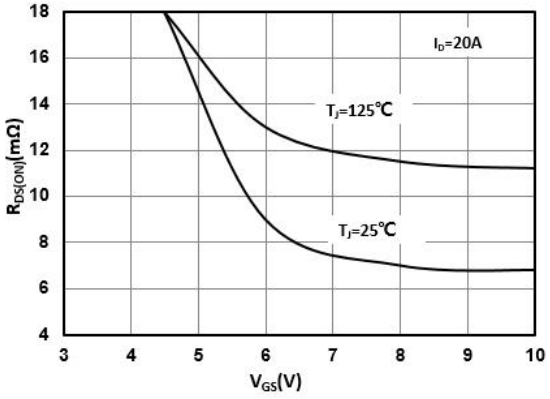


Figure 6 Body Diode Forward Voltage

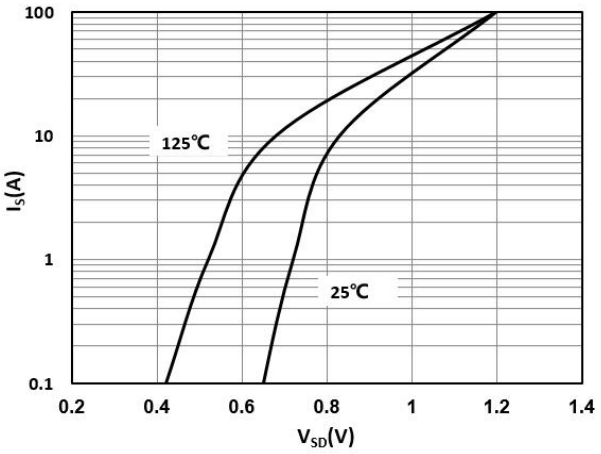


Figure 7 Gate-Charge Characteristics

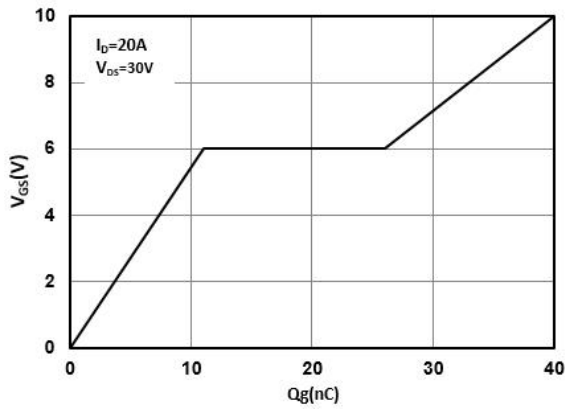


Figure 8 Capacitance Characteristics

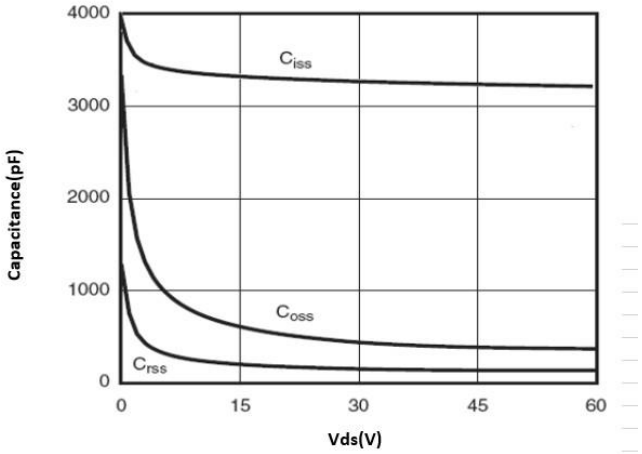


Figure 9 Maximum Forward Biased Safe Operation Area

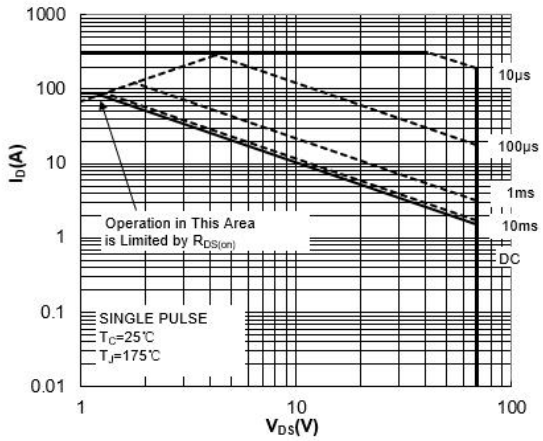


Figure 10 Single Pulse Power Rating Junction-to-Ambient

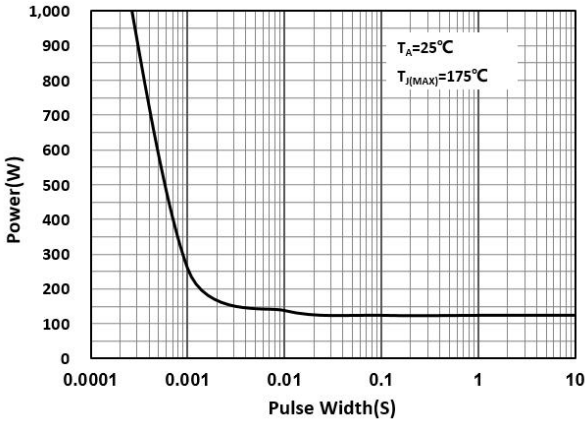
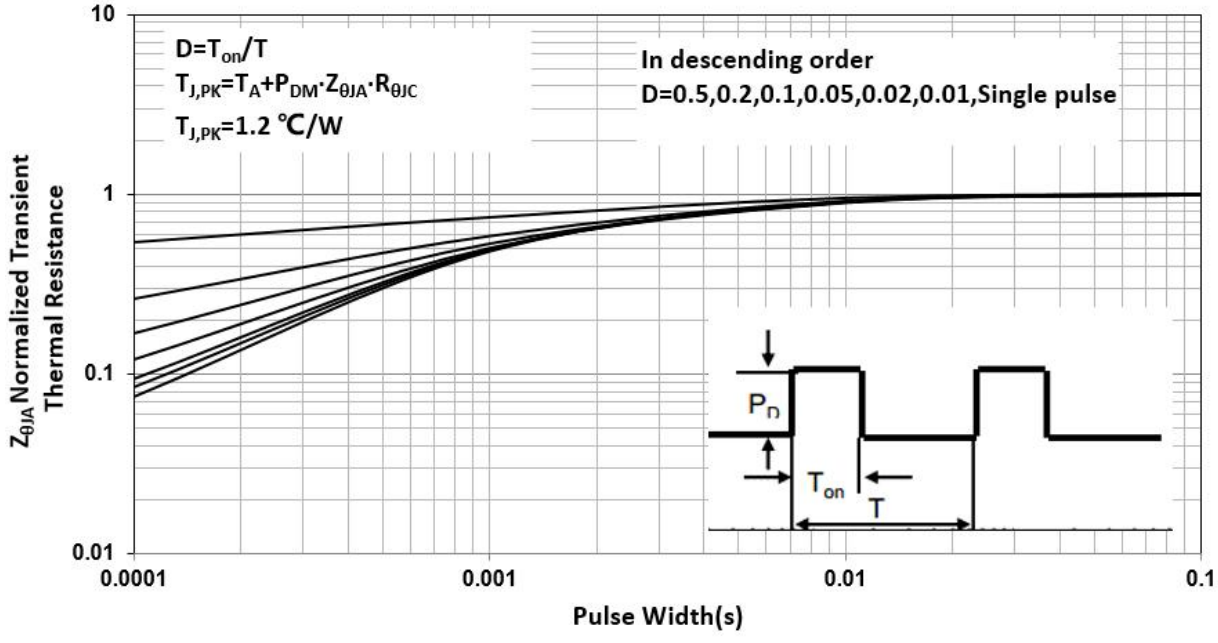
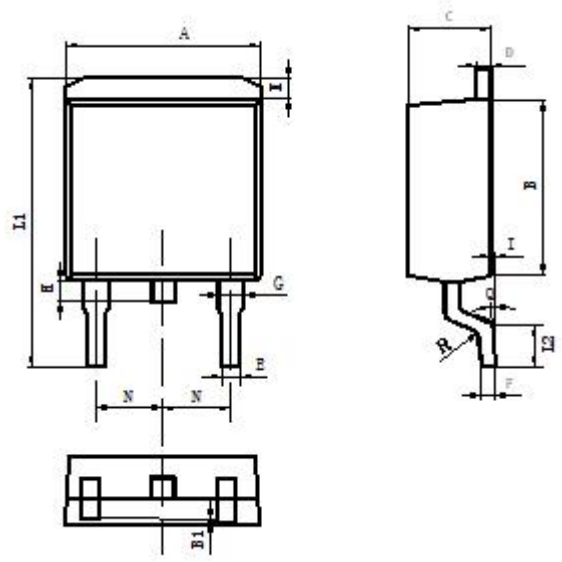


Figure 11 Normalized Maximum Transient Thermal Impedance

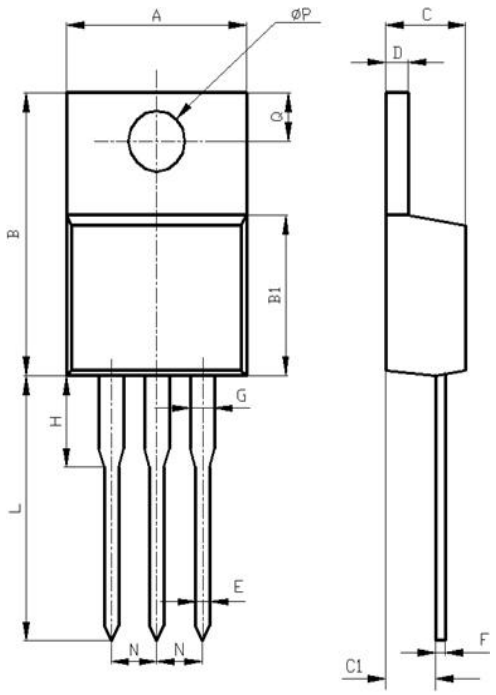


Package Description



Items	Values(mm)	
	MIN	MAX
A	9.80	10.40
B	8.90	9.50
B1	0	0.10
C	4.40	4.80
D	1.16	1.37
E	0.70	0.95
F	0.30	0.60
G	1.07	1.47
H	1.30	1.80
K	0.95	1.37
L1	14.50	16.50
L2	1.60	2.30
I	0	0.2
Q	0°	8°
R	0.4	0.4
N	2.39	2.69

TO-263 Package



Items	Values(mm)	
	MIN	MAX
A	9.60	10.6
B	15.0	16.0
B1	8.90	9.50
C	4.30	4.80
C1	2.30	3.10
D	1.20	1.40
E	0.70	0.90
F	0.30	0.60
G	1.17	1.37
H	2.70	3.80
L	12.6	14.8
N	2.34	2.74
Q	2.40	3.00
ϕp	3.50	3.90

TO-220 Package

NOTE:

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. Please do not exceed the absolute maximum ratings of the device when circuit designing.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. MOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. Shenzhen Minos reserves the right to make changes in this specification sheet and is subject to change withoutprior notice.

CONTACT:

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